

## SPB100N03S203T-VB Datasheet N-Channel 30-V (D-S) MOSFET

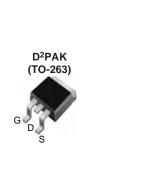
D

0

N-Channel MOSFET

GO

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)		
30	0.0023 at V <sub>GS</sub> = 10 V	150	82 nC		
	0.0032 at V <sub>GS</sub> = 4.5 V	120	02 110		



#### **FEATURES**

- Trench Power MOSFET
- 100 %  $R_g$  and UIS Tested
- Compliant to RoHS Directive 2011/65/EU

#### **APPLICATIONS**

- OR-ing
- Server
- DC/DC •

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V		
Gate-Source Voltage		V <sub>GS</sub>		± 20	
	T <sub>C</sub> = 25 °C		150		
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 70 °C		120		
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	35.8 <sup>b, c</sup>	A	
	T <sub>A</sub> = 70 °C		27 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	500		
Avalanche Current Pulse	0.1 ml	I <sub>AS</sub>	39		
Single Pulse Avalanche Energy L = 0.1 mH		E <sub>AS</sub>	94.8	mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	1-	90 <sup>a, e</sup>		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	3.13 <sup>b, c</sup>	- A	
	T <sub>C</sub> = 25 °C		250 <sup>a</sup>		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C		175		
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.75 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		2.63 <sup>b, c</sup>		
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	$t \le 10 \text{ sec}$	R <sub>thJA</sub>	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.5	0.6		

Notes:

a. Based on  $T_C = 25$  °C. b. Surface mounted on 1" x 1" FR4 board. c. t = 10 sec.

d. Maximum under steady state conditions is 90 °C/W.

<b>SPECIFICATIONS</b> ( $T_J = 25 \text{ °C}$ , unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V		
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		35		- mV/°C		
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 7.5				
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	V		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA		
Zero Gate Voltage Drain Current	1	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	1		1			
	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	90			А		
Drain-Source On-State Resistance <sup>a</sup>	В	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 38.8 A		0.0023		Ω		
	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 37 \text{ A}$		0.0032				
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 38.8 A		160		S		
Dynamic <sup>b</sup>								
Input Capacitance	C <sub>iss</sub>			6201		pF		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1725				
Reverse Transfer Capacitance	C <sub>rss</sub>			970				
		V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 38.8 A		171	257	nC		
Total Gate Charge	Qg			81.5	123			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 15 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 28.8 A		34				
Gate-Drain Charge	Q <sub>gd</sub>			29				
Gate Resistance	Rg	f = 1 MHz		1.4	2.1	Ω		
Turn-On Delay Time	t <sub>d(on)</sub>			18	27	ns		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_{L}$ = 0.625 $\Omega$		11	17			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 24 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		70	105			
Fall Time	t <sub>f</sub>			10	15			
Turn-On Delay Time	t <sub>d(on)</sub>			55	83			
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, R <sub>1</sub> = 0.67 $\Omega$		180	270			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 22.5 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		55	83			
Fall Time	t <sub>f</sub>			12	18			
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			120			
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				120	A		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 22 A		0.8	1.2	V		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	-		52	78	ns		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			70.2	105	nC		
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		27		ns		
Reverse Recovery Rise Time	t <sub>b</sub>			25				

Notes:

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2$  %.

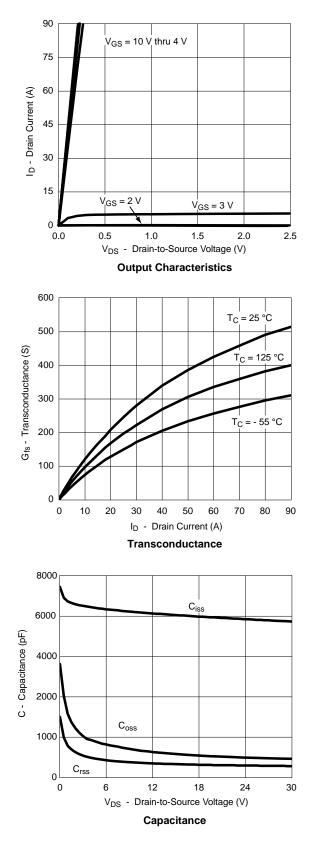
b. Guaranteed by design, not subject to production testing.

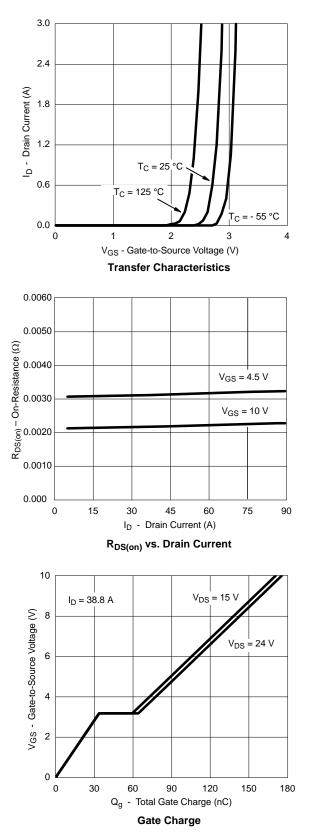
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

VBsemi Bsemi.com



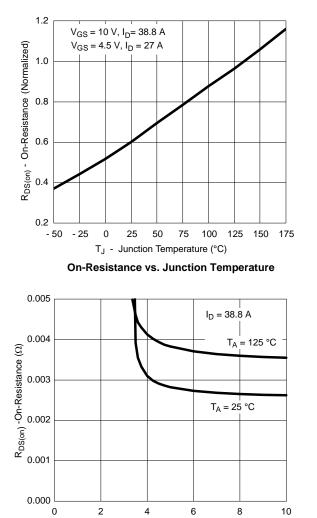
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



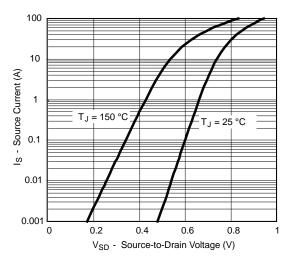




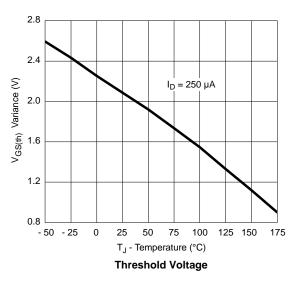
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

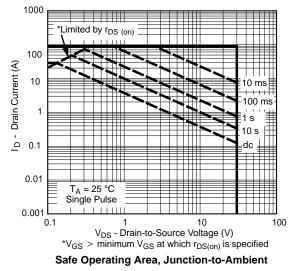


 $V_{GS}$  - Gate-to-Source Voltage (V) R<sub>DS(on)</sub> vs. V<sub>GS</sub> vs. Temperature

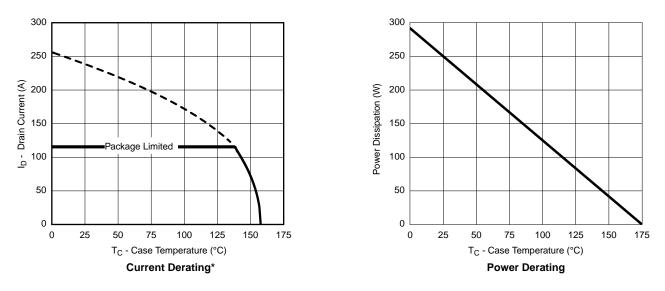












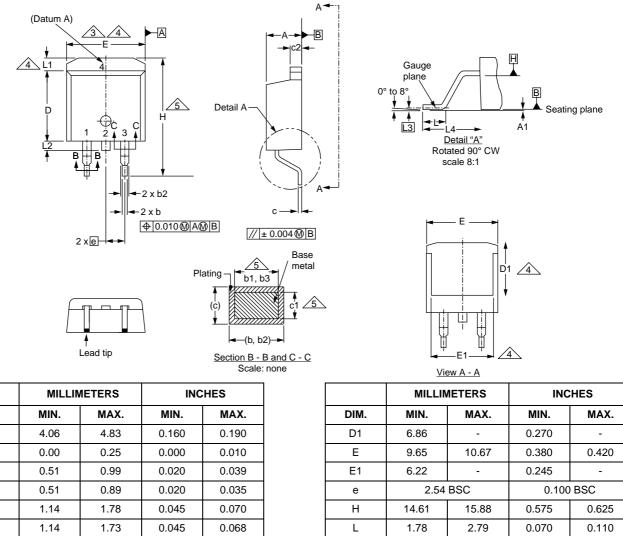
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

\*The power dissipation  $P_D$  is based on  $T_{J(max)} = 175$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





#### **TO-263AB (HIGH VOLTAGE)**



#### ECN: S-82110-Rev. A, 15-Sep-08

0.38

0.38

1.14

8.38

#### DWG: 5970 Notes

DIM.

А

A1

b

b1

b2

b3

с

c1

c2

D

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.

L1

L2

L3

L4

-

-

4.78

1.65

1.78

5.28

0.25 BSC

4. Thermal PAD contour optional within dimension E, L1, D1 and E1.

0.74

0.58

1.65

9.65

0.015

0.015

0.045

0.330

0.029

0.023

0.065

0.380

- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

0.066

0.070

0.208

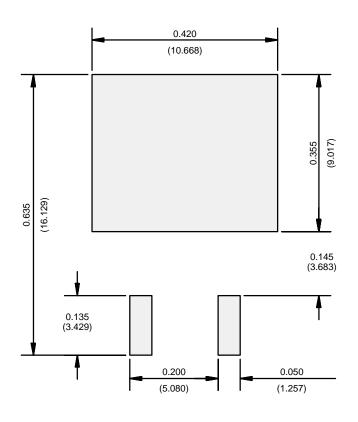
0.010 BSC

-

0.188



### **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



# Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

## **Material Category Policy**

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be RoHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.